# TOSHIBA

#### TOSHIBA SUPER FAST RECOVERY RECTIFIER SILICON DIFFUSED TYPE

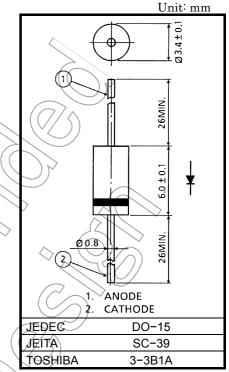
# 1NU41

### SWITCHING MODE POWER SUPPLY APPLICATIONS

- Repetitive Peak Reverse Voltage  $: V_{RRM} = 1000V$
- Average Forward Current  $I_{\rm F}({\rm AV}) = 1.0{\rm A}$
- Very Fast Reverse-Recovery Time  $: t_{rr} = 100$ ns

## ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	1000	V
Average Forward Current	I <sub>F (AV)</sub>	1.0	(A)
Peak One Cycle Surge Forward Current (Non-Repetitive)	I <sub>FSM</sub>	10 (50H <sub>Z</sub> )	A
Junction Temperature	т.	11 (60Hz) -40 to 150	⊃°C
Storage Temperature Range	T <sub>stq</sub>	-40 to 150	<del>ງ</del> ວໍ
	· sig		3



Weight: 0.42g

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e.

operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

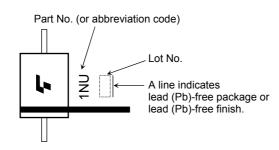
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report

and estimated failure rate, etc).

## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

	TEST CONDITION	MIN	TYP.	MAX	UNIT	
VFM	$I_{\text{FM}} = 1.0A$	_	_	3.3	V	
I <sub>RRM</sub>	V <sub>RRM</sub> = Rated	_	—	100	μA	
ţrr>	I <sub>F</sub> = 1A, di / dt = -30A / μs	_	_	100	ns	
< tr	I <sub>F</sub> = 1.0A	_	300	_	ns	
Rth (j-a)	Junction to Ambient	_	_	60	°C / W	
Rth (j-t)	Junction to Lead	_	_	34	°C / W	
	VFM IRRM trr tfr Rth (j-a)	VFMIFM = 1.0AIRRMVRRM = RatedtrrIF = 1A, di / dt = $-30A / \mu s$ trrIF = 1.0AtrrIF = 1.0ARth-(j-a)Junction to Ambient	VFMIFM = 1.0AIRRMVRRM = Rated $t_{rr}$ IF = 1A, di / dt = -30A / $\mu$ s $t_{rr}$ IF = 1.0A $t_{rr}$ IF = 1.0ARth (j-a)Junction to Ambient	VFM         IFM = 1.0A         -         -           IRRM         VRRM = Rated         -         -           trr         IF = 1A, di / dt = -30A / $\mu$ s         -         -           trr         IF = 1.0A         -         300           Rth (j-a)         Junction to Ambient         -         -	VFM         IFM = 1.0A         -         -         3.3           IRRM         VRRM = Rated         -         -         100           trr         IF = 1A, di / dt = -30A / $\mu$ s         -         -         100           trr         IF = 1.0A         -         300         -           Rth.(j-a)         Junction to Ambient         -         -         60	

#### MARKING



Abbreviation Code	Part No.		
1NU	1NU41		

# **TOSHIBA**

#### **Handling Precaution**

The absolute maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend when you design a circuit with a device.

- $V_{RRM}$ : We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of  $V_{RRM}$  for a DC circuit and be no greater than 50% of that of  $V_{RRM}$  for an AC circuit.  $V_{RRM}$  has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.
- IF(AV): We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF(AV). Carry out adequate heat design. If you can't design a circuit with excellent heat radiation, set the margin by using an allowable Tamax-IF(AV) curve.

This rating specifies the non-repetitive peak current in one cycle of a 50 Hz sine wave, condition angle 180. Therefore, this is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.

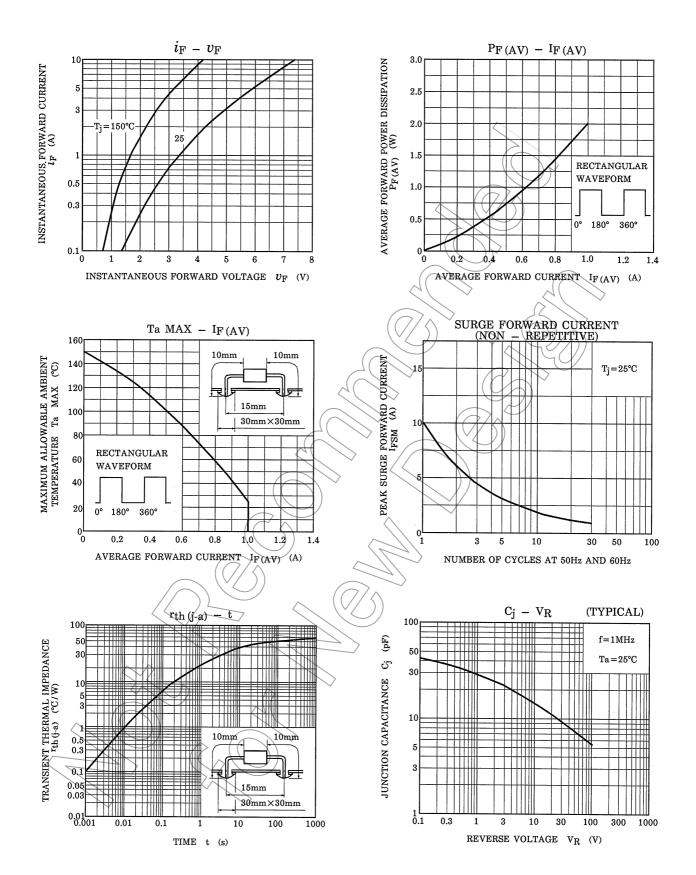
We recommend that a device be used at a Tj of below 120°C under the worst load and heat radiation conditions.

Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.

Organic silicon is used as encapsulation material for this product, which is resin seal product. Therefore, it is difficult to seal siloxane coming from silicone completely in this product. When using this product, please consider above.

Please refer to the Rectifiers databook for further information.

## TOSHIBA



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4